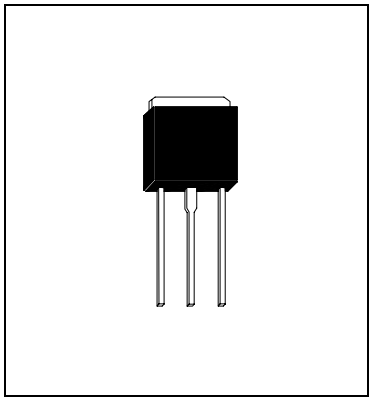
HTL294MI

PNP EPITAXIAL PLANAR TRANSISTOR



Description

The HTL294MI is designed for high voltage low power switching applications especially for use in telephone and telecommunication circuits.

Absolute Maximum Ratings

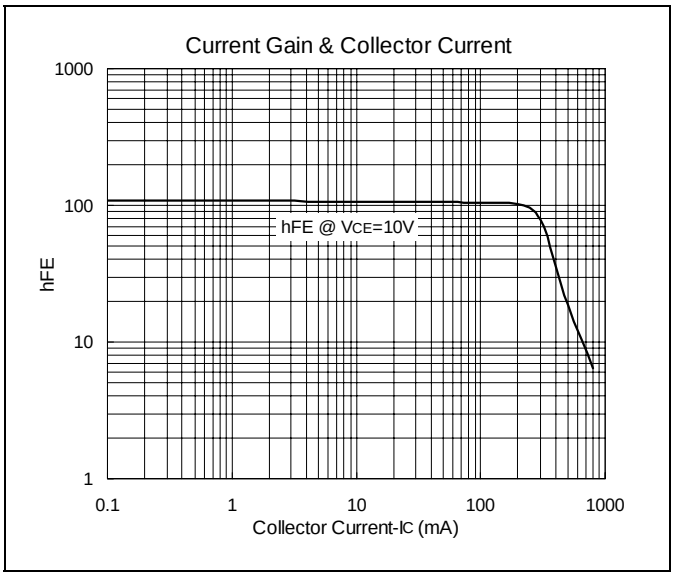
- Maximum Temperatures
  Storage Temperature ..... -55 ~ +150 °C
  Junction Temperature ..... 150 °C Maximum
- Maximum Power Dissipation
  Total Power Dissipation (Ta=25°C) ..... 1 W
- Maximum Voltages and Currents (Ta=25°C)
  VCBO Collector to Base Voltage ..... -400 V
  VCEO Collector to Emitter Voltage ..... -400 V
  VEBO Emitter to Base Voltage ..... -6 V
  IC Collector Current ..... -400 mA

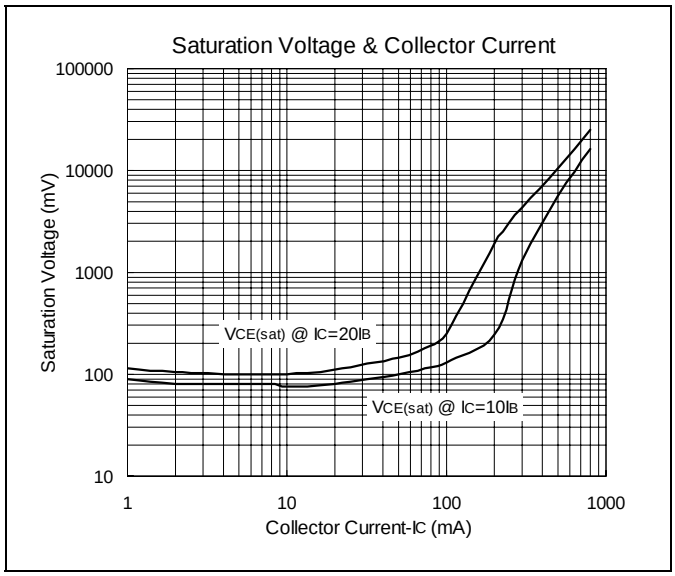
Characteristics (Ta=25°C)

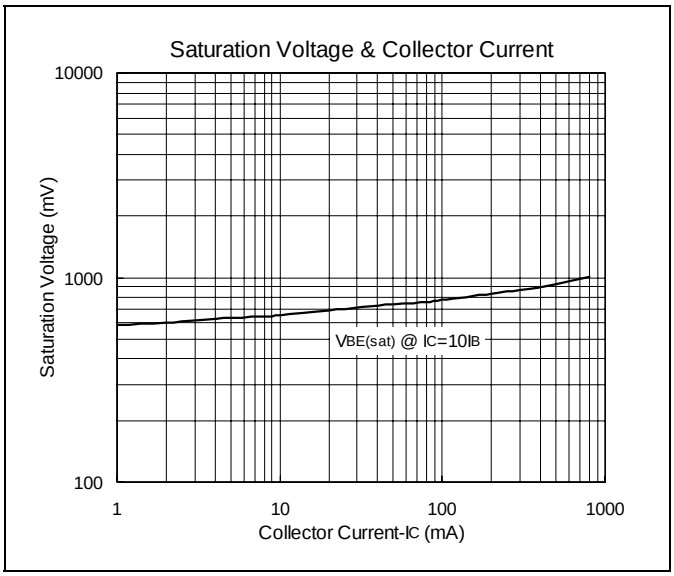
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-400	-	-	V	IC=-100uA, IE=0
BVCEO	-400	-	-	V	IC=-1mA, IB=0
BVEBO	-6	-	-	V	IE=10uA
ICBO	-	-	-1	uA	VCB=-400V, IE=0
ICES	-	-	-10	uA	VCE=-400V, IE=0
IEBO	-	-	-0.2	uA	VEB=-6V, IC=0
*VCE(sat)1	-	-	-200	mV	IC=-10mA, IB=-1mA
*VCE(sat)2	-	-	-300	mV	IC=-50mA, IB=-5mA
*VCE(sat)3	-	-	-1.2	V	IC=-80mA, IB=-4mA
*VBE(sat)	-	-	-750	mV	IC=-10mA, IB=-1mA
*hFE1	50	-	-		VCE=-10V, IC=-1mA
*hFE2	60	-	250		VCE=-10V, IC=-20mA
*hFE3	50	-	-		VCE=-10V, IC=-80mA
fT	30	-	-	MHz	VCE=-20V, IE=-10mA, f=1MHz
Cob	-	-	30	pF	VCB=-20V, f=1MHz, IE=0

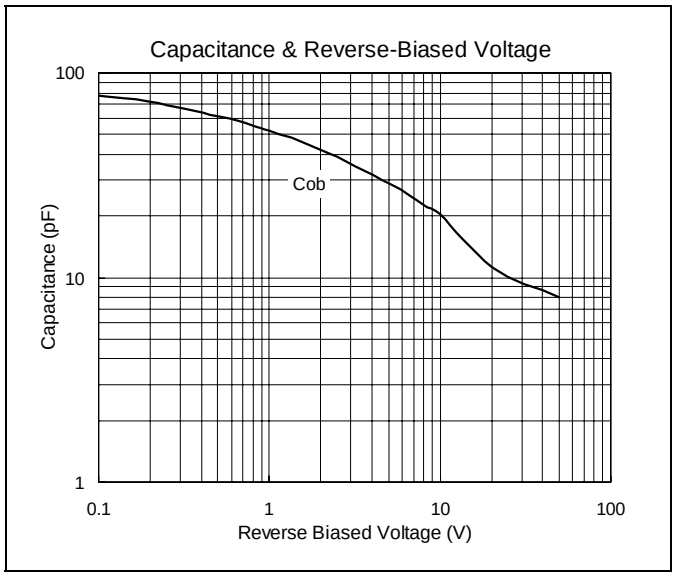
*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

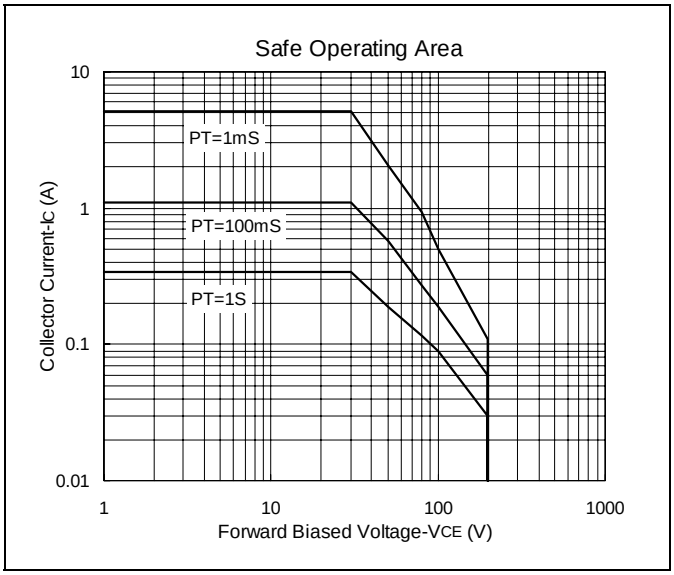
Characteristics Curve

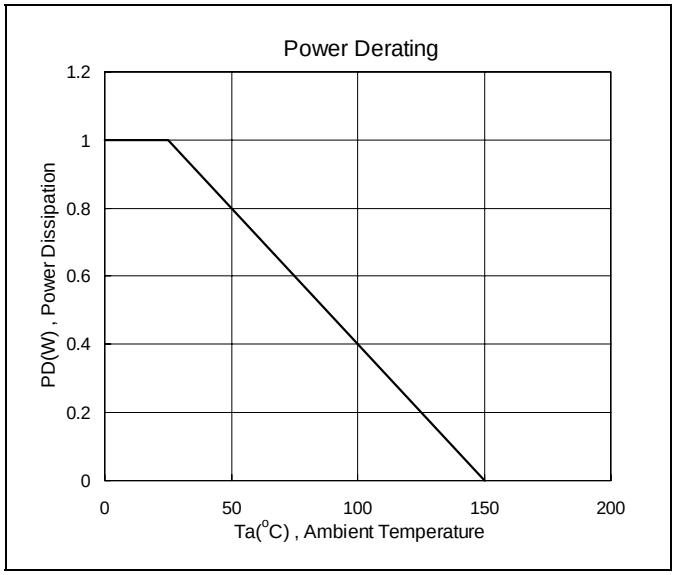




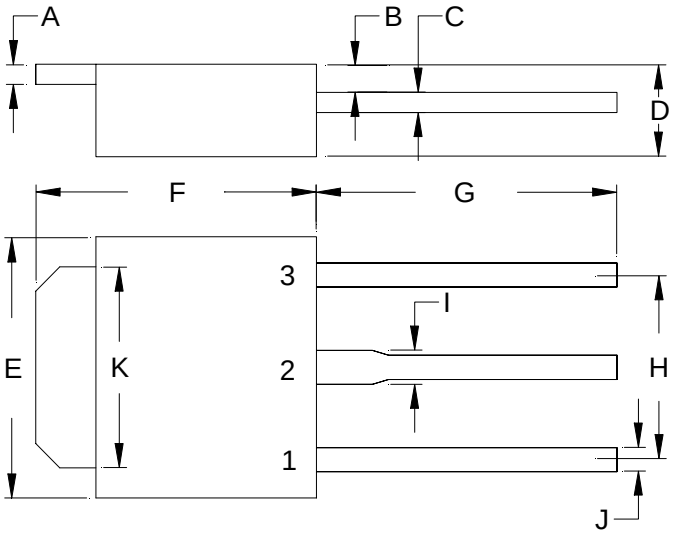




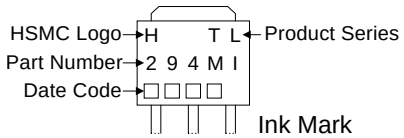




TO-251 Dimension



Marking :



Style : Pin 1.Base 2.Collector 3.Emitter

3-Lead TO-251 Plastic Package
HSMC Package Code : I

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.2559	-	6.50	-
B	0.0354	0.0591	0.90	1.50	H	-	*0.1811	-	*4.60
C	0.0177	0.0236	0.45	0.60	I	-	0.0354	-	0.90
D	0.0866	0.0945	2.20	2.40	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2677	0.2835	6.80	7.20					

Notes : 1.Dimension and tolerance based on our Spec. dated May. 24,1995.
2.Controlling dimension : millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

Head Office And Factory :

- **Head Office** (Hi-Sincerity Microelectronics Corp.) : 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
  Tel : 886-2-25212056 Fax : 886-2-25632712, 25368454
- **Factory 1 :** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
  Tel : 886-3-5983621~5 Fax : 886-3-5982931